Symbol | Hit Count | Finished Hole Size | Plated Hole Type
---|---|---|---
.| 20 | 7.80~8.1 (0.200~0.206) | PTN Round
.| 182 | 10.10~10.1 (0.255~0.256) | PTN Round
.| 223 | 12.30~12.3 (0.306~0.308) | PTN Round
.| 223 | 12.30~12.3 (0.306~0.308) | PTN Round
.| 40 | 14.00~14.0 (0.355~0.356) | PTN Round
.| 10 | 14.00~14.0 (0.355~0.356) | PTN Round
.| 10 | 14.00~14.0 (0.355~0.356) | PTN Round
.| 4 | 22.50~22.5 (0.570~0.571) | PTN Round

486 Total

DRILL TECHNIQUE:
For PTN - 1P2,
22mil drill X 0.120mil
drill X 0.120mil
7.80mil drill X 0.200mil
This is not an impedance controlled board
All sizes are tested except the sizes on thermal pads.
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